

# SOT1059-1

plastic extremely thin small outline package; no leads; 10 terminals; UTLP based; body 1 x 2.5 x 0.5 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	XSON10U
<b>Package type industry code</b>	XSON10U
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-1-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	0.9	-	1	1.1	mm
A	seated height	[tbd]	-	0.5	0.5	mm
A <sub>2</sub>	package height	[tbd]	-	0.5	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	

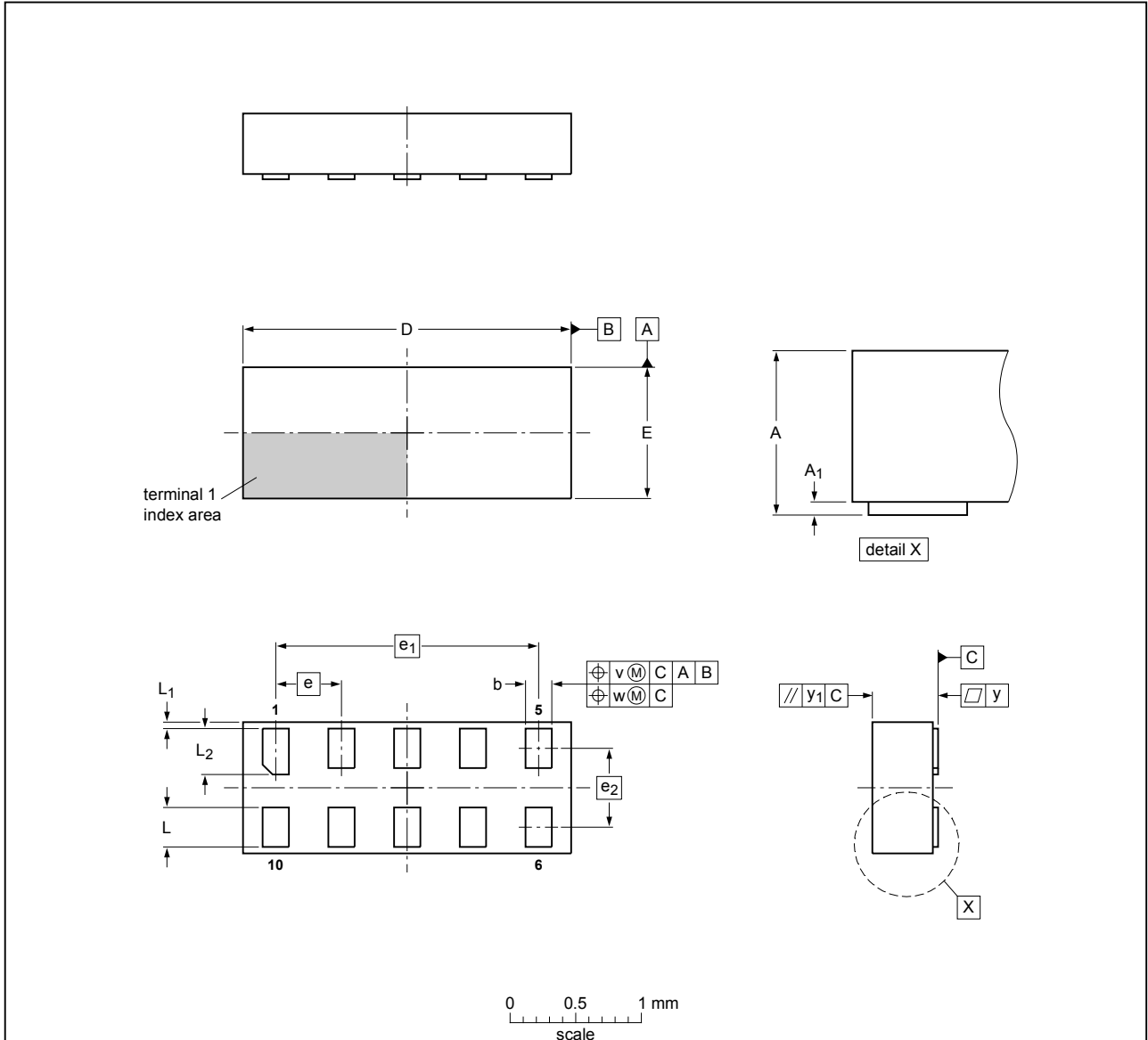


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## 2. Package outline

XSON10U: plastic extremely thin small outline package; no leads; 10 terminals; UTLP based; body 1 x 2.5 x 0.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	L	L <sub>1</sub>	L <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	0.5	0.05 0.00	0.25 0.15	2.6 2.4	1.1 0.9	0.5	2	0.6	0.4 0.2	0.15 0.00	0.45 0.25	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1059-1	---		---			07-12-20 08-01-18

Fig. 1. Package outline XSON10U (SOT1059-1)

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### 3. Legal information

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Date of release: 8 February 2016

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